

# PHOTONICS Research

## Nearly lattice-matched molybdenum disulfide/gallium nitride heterostructure enabling high-performance phototransistors

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Molybdenum disulfide (MoS<sub>2</sub>)-based phototransistors are attractive for optical electronics in a large-scale size, such as transparent touch screens. However, most of the work done over the past decade has been on an opaque SiO<sub>2</sub>/Si wafer with a small size (micrometer to millimeter). In this work, a large-scale multilayer MoS<sub>2</sub>-based phototransistor has been fabricated on a transparent freestanding gallium nitride (GaN) wafer using a scalable chemical vapor deposition method. Due to the near lattice match and small thermal expansion mismatch between GaN and MoS<sub>2</sub>, the as-grown multilayer MoS<sub>2</sub>-on-GaN film shows high material quality in terms of low full width at half-maximum ( $\sim 5.16 \text{ cm}^{-1}$ ) for the E<sub>2g</sub><sup>1</sup> Raman mode and a high absorption coefficient ( $\sim 10^6 \text{ cm}^{-1}$ ) in the wavelength range of 405–638 nm. Under a wavelength of 405 nm at an incident power of 2 mW and applied voltage of 9 V, the fabricated MoS<sub>2</sub>-on-GaN phototransistor achieved a maximum responsivity of 17.2 A/W, a photocurrent gain of 53.6, and an external quantum efficiency of 5289%, with specific detectivity ( $\sim 10^{10}$ – $10^{12}$  Jones) and low noise equivalent power ( $10^{-12}$ – $10^{-14} \text{ W/Hz}^{1/2}$ ) in the visible range of 405–638 nm. A typical response time of 0.1–4 s in the ambient air has also been recorded for the demonstrated MoS<sub>2</sub>-on-GaN phototransistor. Our work paves a technologic stepping stone for MoS<sub>2</sub>-based phototransistors for multifunctional transparent and touch-based optoelectronics in the future. © 2019 Chinese Laser Press

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### 1. INTRODUCTION

Molybdenum disulfide (MoS<sub>2</sub>), as a typical example of the two-dimensional material family, is a layered transition-metal dichalcogenide semiconductor that has no surface dangling bonds and high thermal stability ( $\sim 1100^\circ\text{C}$ ). Due to its high carrier mobility, reasonable bandgap, and high light absorbance, MoS<sub>2</sub> has attracted intense research interest because of its potential applications in nanoelectronics, including touch-sensor panels, image sensors, solar cells, and communication devices [1–11]. As compared with graphene (zero bandgap), multilayer (ML) MoS<sub>2</sub> is an indirect semiconductor with a bandgap energy of 1.2 eV, while single-layer (1L) MoS<sub>2</sub> is a direct semiconductor (1.8 eV). MoS<sub>2</sub>-based electronic devices with a high current

on/off ratio ( $10^6$ – $10^8$ ), mobility up to  $\sim 140$ – $200 \text{ cm}^2 \cdot \text{V}^{-1} \cdot \text{s}^{-1}$ , and low subthreshold swing ( $\sim 70$ – $80 \text{ mV/decade}$ ) have been reported in the literature [12–14]. On the other hand, the MoS<sub>2</sub>-based phototransistors have also achieved significant progress since the first demonstration of exfoliated monolayer MoS<sub>2</sub> phototransistors with a responsivity of  $\sim 7.5 \text{ mA/W}$  at a wavelength of 750 nm [15]. The responsivity of  $\sim 880 \text{ A/W}$  has also been demonstrated on the exfoliated monolayer MoS<sub>2</sub> phototransistor in the depletion operation region [1]. The response time or the rise time is on the order of a few seconds, which can be further reduced to microseconds with the help of a gate pulse to reset the conductivity of the device channel, since the trap state plays an important role in the photocurrent

generation mechanism. Given the large surface-to-volume ratio, the absorbates play a major role in the properties of layered MoS<sub>2</sub> material, and changed absorbates also reduce the photoresponse as they suppress the lifetime of trapped carriers by acting as recombination centers. Higher responsivity of  $\sim 2200$  A/W is obtained for the monolayer MoS<sub>2</sub> phototransistor in the vacuum condition [16]. Most of these devices were based on small size MoS<sub>2</sub> microsheets fabricated by mechanical exfoliation from bulk crystals or chemical vapor deposition (CVD) synthesis. Nevertheless, the applications were restricted by the limited capability in producing high-quality and uniform large-area MoS<sub>2</sub> film. To integrate MoS<sub>2</sub> into scalable manufacturing, a large-scale synthesis method to fabricate high-quality MoS<sub>2</sub> film with precise control of thickness is essential. Bottom-up methods such as CVD [17], thermal evaporation [18,19], magnetron sputtering [20], electrochemical lithiation processes [21,22], and sulfurization of molybdenum oxides [23] have been introduced for fabricating large-scale layered MoS<sub>2</sub> on a SiO<sub>2</sub>/Si substrate. The reported mobility obtained from the exfoliated monolayer MoS<sub>2</sub> shows a significant degradation in the range of  $0.1\text{--}10\text{ cm}^2 \cdot \text{V}^{-1} \cdot \text{s}^{-1}$  [24,25]. The field effect mobility at room temperature of MoS<sub>2</sub> is limited by phonon scattering in the range of  $200\text{--}500\text{ cm}^2 \cdot \text{V}^{-1} \cdot \text{s}^{-1}$  [26]. Charge traps (up to  $\sim 10^{15}\text{ cm}^{-2}$ ) located at the interface between the MoS<sub>2</sub> and SiO<sub>2</sub> layer, and also charged impurity scattering within the SiO<sub>2</sub> layer, have been identified as the main causes for low mobility in MoS<sub>2</sub> electronic devices at room temperature [10,27,28]. In order to eliminate the effect due to the underlying SiO<sub>2</sub> layer, such as charge scattering, it is proposed in this work that the MoS<sub>2</sub> film is grown on nearly lattice-matched (0.8%) freestanding (FS) gallium nitride (GaN), which has a wide energy bandgap (3.4 eV) and is highly chemically stable and transparent. Recently, MoS<sub>2</sub>-based photodetectors on sapphire have been demonstrated, but the devices show a low responsivity (less than 1 A/W), which is due to the challenge of growing high-quality MoS<sub>2</sub> film on the large lattice mismatch ( $\sim 50\%$ ) and the large thermal expansion coefficient (TEC) mismatch sapphire substrate (lattice  $a \sim 0.4758\text{ nm}$ ;  $\text{TEC} \sim 7.5 \times 10^{-6}\text{ K}^{-1}$ ) [29,30]. A bulk GaN wafer was used to ensure that the GaN wafer has zero local strain, and its defect density is below  $\sim 10^4\text{--}10^5\text{ cm}^{-2}$ , which is much lower as compared to the defect density of the SiO<sub>2</sub> layer [31,32]. As compared with monolayer MoS<sub>2</sub>, ML MoS<sub>2</sub> film is attractive for phototransistor application, which is not only due to its smaller bandgap, extended detection range, and larger absorption, but also the easier growth in a large-scale uniform film. However, the responsivity of the ML MoS<sub>2</sub> phototransistor without any boost technique is lower, which could be due to its indirect bandgap.

In order to achieve better quality, as-grown MoS<sub>2</sub> film, large-scale ML MoS<sub>2</sub> film, has been grown on the nearly perfect lattice-matched and transparent FS GaN wafer in this work. MoS<sub>2</sub>-on-GaN phototransistors have been fabricated in a typical semiconductor fabrication process and fully characterized. Detailed material studies using Raman spectroscopy, X-ray photoelectron spectroscopy (XPS), transmission electron microscopy (TEM), and absorption techniques have been carried out. Maximum responsivity  $R$  of 17.2 A/W, highest

specific detectivity  $D$  of  $\sim 1.8 \times 10^{12}$  Jones, and the lowest noise equivalent power (NEP) of  $\sim 9.6 \times 10^{-14}\text{ W/Hz}^{1/2}$  have been achieved for the fabricated MoS<sub>2</sub>-on-GaN phototransistors with a typical response time of 0.1–4 s in the visible wavelength range under ambient air.

## 2. METHOD

### A. Sample Preparation and Device Fabrication

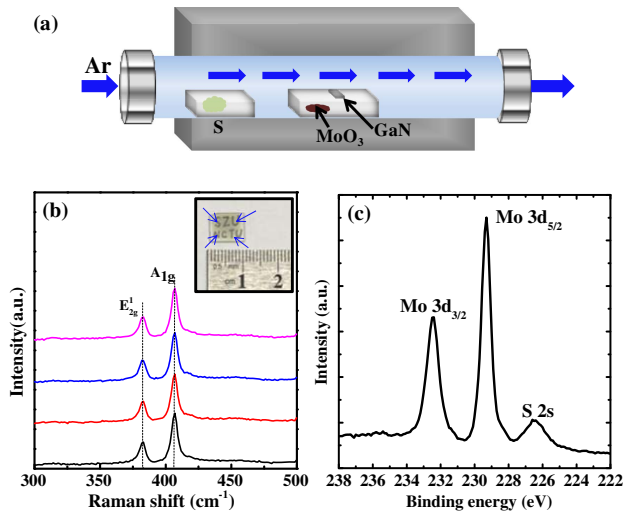
Two-inch FS GaN substrate (350  $\mu\text{m}$  thick) with (0001) orientation was grown by hydride vapor phase epitaxy (HVPE). HCl/metal Ga, ammonia, and a N<sub>2</sub>/H<sub>2</sub> mixture were used as the Ga source, nitrogen source, and carrier gas, respectively. The growth rate was typically about 150  $\mu\text{m/h}$ . After HVPE growth, the Ga surface was further polished by chemical mechanical polishing (CMP). The FS GaN substrate went through a precleaning process, which consisted of a 5-min acetone, a 5-min isopropanol degreasing step, and a 2-h piranha solution (H<sub>2</sub>O<sub>2</sub>:H<sub>2</sub>SO<sub>4</sub> = 1:3) immersion step for the organic residue removal. 0.08 mg of MoO<sub>3</sub> was spread uniformly over 2–3 cm in an alumina crucible and FS GaN wafer growth substrate was placed upside down on the crucible. Sulfur powder (1 g) was placed upstream in 30 sccm of argon gas flow. Few layer FS MoS<sub>2</sub> was grown at 800°C for 5 min. Ti(5 nm)/Al(50 nm) was directly deposited as an electrode using a shallow mask without a film transfer process. Due to the limitation of the CVD chamber diameter, 50 mm FS-GaN was cut into small pieces for CVD growth (1 cm by 1 cm).

### B. Materials and Electrical Characterizations

Raman spectra were collected in a Renishaw inVia confocal system in the backscattering configuration. The wavelength of the laser was 514.5 nm (2.41 eV) from an argon ion laser; a grating of 2400 grooves  $\cdot \text{mm}^{-1}$  was used to obtain more details of the line shapes of the Raman band. The laser power on the sample was set at around 1.0  $\mu\text{W}$  to avoid laser-induced heating. The Si peak at 520  $\text{cm}^{-1}$  was used as a reference for wavelength calibration. The absorbance spectra were measured with a SHIMADZU-2450 UV-visible spectrometer in the spectral range of 380–900 nm. XPS profiles were obtained using a VG ESCALAB 220i-XL system with a monochromatized Al K $\alpha$  (1486.6 eV) X-ray source (a constant pass energy of 20 eV). A Keithley 4200-SCS semiconductor analyzer was used to measure the  $I$ - $V$  characteristics and responsivity of the MoS<sub>2</sub>-on-GaN phototransistor.

## 3. RESULTS AND DISCUSSION

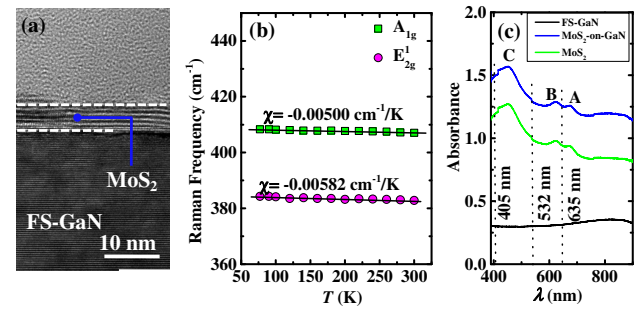
Figure 1(a) schematically illustrates the experimental CVD setup used in this work. An FS undoped GaN wafer was used as the starting substrate for the one-step direct growth of ML MoS<sub>2</sub> film, in which MoO<sub>3</sub> and sulfur powder were used as precursors. The detailed growth process can be found in the previous published work [33]. Due to the limitation of the furnace diameter, the size of the FS GaN wafer is 1 cm by 1 cm. The as-grown MoS<sub>2</sub>-on-GaN sample was characterized using Raman measurement. As shown in Fig. 1(b), Raman spectra from the four locations indicated by the arrows shown in the inset are shown. The A<sub>1g</sub> mode related to the out-of-plane vibration of sulfur atoms and the E<sub>2g</sub><sup>1</sup> mode associated with the



**Fig. 1.** (a) Illustration of the experimental setup of CVD in this work. The Ga face of the FS GaN wafer is faced down, and ML MoS<sub>2</sub> is grown on the Ga surface. The growth temperature and duration time were 800°C and 5 min, respectively. (b) Raman spectra of the as-grown MoS<sub>2</sub>-on-GaN sample from the four locations indicated by the arrows shown in the inset, and the letters SZU and NCTU being an abbreviation of “Shenzhen University” and “National Chiao Tung University” are clearly seen. (c) Core-level XPS spectrum of Mo 3d and S 2s of the as-grown MoS<sub>2</sub>-on-GaN sample.

in-plane vibration of Mo and sulfur atoms, can be clearly observed in Fig. 1(b). The MoS<sub>2</sub> crystalline quality can be reflected by the full width at half-maximum (FWHM) of the E<sub>2g</sub><sup>1</sup> Raman peak. The value of FWHM for the E<sub>2g</sub><sup>1</sup> Raman peak in this work is about ~5.16 cm<sup>-1</sup>, which is larger than 3.7 cm<sup>-1</sup> of the exfoliated MoS<sub>2</sub> film, but smaller than 6.5 cm<sup>-1</sup> of as-grown MoS<sub>2</sub> film by CVD [33]. This could be related with certain crystalline imperfections, for example, sulfur vacancies and crystalline grain boundary in the synthesized thin film. The lower FWHM value of the E<sub>2g</sub><sup>1</sup> for as-grown MoS<sub>2</sub>-on-GaN film does indicate the advantage by the lattice-matched MoS<sub>2</sub>-on-GaN technique. The thickness of MoS<sub>2</sub> film can be estimated by the frequency difference ( $\Delta k$ ) between the E<sub>2g</sub><sup>1</sup> and A<sub>1g</sub><sup>1</sup> Raman peaks. As shown in Fig. 1(b), the  $\Delta k$  value of the synthesized MoS<sub>2</sub>-on-GaN film is about 24.97 cm<sup>-1</sup>, which corresponds to more than 5–6 layers. According to the Raman peak position for the different locations, the uniformity of as-grown MoS<sub>2</sub>-on-GaN is excellent, since the Raman peak position has little shift for the different locations. XPS measurement was employed to determine the composition of MoS<sub>2</sub> film. Figure 1(c) shows the core-level XPS spectrum of Mo 3d and S 2s. The peak binding energy for Mo 3d<sub>3/2</sub>, Mo 3d<sub>5/2</sub>, and S 2s is 232.45, 229.32, and 226.45 eV, respectively, which is consistent with reported values in the literature. Also, the peak (~235.6 eV) related to Mo-O bonding is absent here, indicating MoO<sub>x</sub> overdeposition does not occur here. The S: Mo atomic ratio is estimated to be 2.03, which is close to the stoichiometric MoS<sub>2</sub>, and the S 2s peak is located at 226.45 eV, which is the characteristic of the stoichiometric MoS<sub>2</sub> [34,35].

Figure 2(a) shows the cross-sectional TEM image of the as-grown MoS<sub>2</sub>-on-GaN sample. The measured MoS<sub>2</sub> film



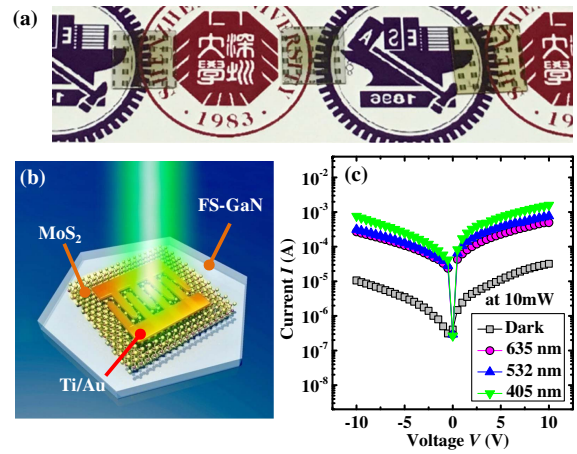
**Fig. 2.** (a) Cross-sectional TEM image of the as-grown MoS<sub>2</sub>-on-GaN sample. The measured MoS<sub>2</sub> film thickness is ~5 nm, and the number of MoS<sub>2</sub> layers is ~5 layers. (b) Effect of temperature variation on the Raman modes of A<sub>1g</sub> and E<sub>2g</sub><sup>1</sup> modes of MoS<sub>2</sub>-on-GaN film; (c) absorbance of FS GaN, as-grown MoS<sub>2</sub>-on-GaN film, and the MoS<sub>2</sub> layer as a function of incident wavelength. The absorbance of MoS<sub>2</sub> could be obtained by subtracting the absorbance value of FS GaN from that of the as-grown MoS<sub>2</sub>-on-GaN sample.

thickness is ~5 nm, and the number of MoS<sub>2</sub> layers is ~5, which is consistent with the Raman frequency difference ( $\Delta k$ ). Figure 2(b) shows the effect of temperature variation on the Raman modes of the A<sub>1g</sub> and E<sub>2g</sub><sup>1</sup> modes of MoS<sub>2</sub>-on-GaN film. Temperature-dependent Raman studies of the as-grown MoS<sub>2</sub>-on-GaN film and as-grown MoS<sub>2</sub>-on-SiO<sub>2</sub> film under the same growth condition in the range of 77–300 K under a 514 nm excitation laser were carried out. The peak positions for A<sub>1g</sub> and E<sub>2g</sub><sup>1</sup> modes versus temperature were fitted using the Grüneisen model:  $\omega(T) = \omega_0 + xT$ , where  $\omega_0$  is the Raman peak position at 0 K,  $x$  is the first-order temperature coefficient, and  $T$  is the temperature. The slope of fitted lines gives the first-order temperature coefficient, as shown in Fig. 2(b). The first-order temperature coefficients  $x$  of the A<sub>1g</sub> and E<sub>2g</sub><sup>1</sup> modes of as-grown MoS<sub>2</sub>-on-GaN film are -0.00500 cm<sup>-1</sup>/K and -0.00582 cm<sup>-1</sup>/K, respectively. Similarly, the first-order temperature coefficients  $x$  of the A<sub>1g</sub> and E<sub>2g</sub><sup>1</sup> modes of as-grown MoS<sub>2</sub>-on-SiO<sub>2</sub> film were also measured to be -0.00520 cm<sup>-1</sup>/K and -0.00490 cm<sup>-1</sup>/K, respectively. The first-order temperature coefficient  $x$  of the A<sub>1g</sub> mode related to out-of-plane vibration of sulfur atoms has little difference between as-grown MoS<sub>2</sub>-on-GaN film and as-grown MoS<sub>2</sub>-on-SiO<sub>2</sub> film. However, the first-order temperature coefficient  $x$  of the E<sub>2g</sub><sup>1</sup> mode for as-grown MoS<sub>2</sub>-on-GaN film is ~19% higher than that of as-grown MoS<sub>2</sub>-on-SiO<sub>2</sub> film. The E<sub>2g</sub><sup>1</sup> Raman mode of MoS<sub>2</sub> is a stress-sensitive in-plane vibration mode. Due to the large TEC mismatch between MoS<sub>2</sub> ( $1.2 \times 10^{-5}$  K<sup>-1</sup>) and SiO<sub>2</sub> ( $5.5 \times 10^{-7}$  K<sup>-1</sup>), tensile strain within the as-grown MoS<sub>2</sub> film on SiO<sub>2</sub> is acquired during the cool-down step of CVD growth. As compared with MoS<sub>2</sub>-on-SiO<sub>2</sub> film, the TEC mismatch between MoS<sub>2</sub> ( $1.2 \times 10^{-5}$  K<sup>-1</sup>) and GaN ( $3.2 \times 10^{-6}$  K<sup>-1</sup>) is smaller, or tensile strain within the MoS<sub>2</sub>-on-GaN film is smaller [36]. Due to the smaller tensile strain within the MoS<sub>2</sub>-on-GaN film, the first-order temperature coefficient  $x$  of the E<sub>2g</sub><sup>1</sup> mode is slightly higher than that of MoS<sub>2</sub>-on-SiO<sub>2</sub> film, since the thermal stability can be enhanced by additional stress [36]. Figure 2(c) shows the absorbance of FS GaN and as-grown MoS<sub>2</sub>-on-GaN as a function



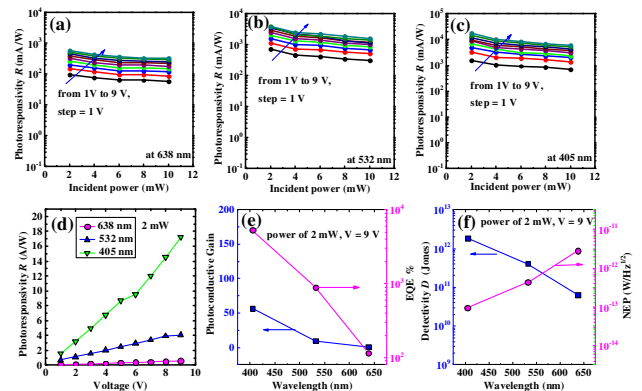
of incident wavelength. Based on the measured absorbance values of FS GaN and as-grown MoS<sub>2</sub>-on-GaN, the absorbance value of MoS<sub>2</sub> film could be calculated by subtracting the absorbance value of FS GaN from that of as-grown MoS<sub>2</sub>-on-GaN, and plotted as a function of incident wavelength in Fig. 2(c). Two excitonic peaks (A and B) located at 672.40 nm and 622.61 nm, respectively, are observed for MoS<sub>2</sub> film, and this arises from the K point of the Brillouin zone. The energy difference between exciton A and exciton B is due to the spin-orbital splitting in the valence band of MoS<sub>2</sub>. In addition to band-edge associated excitons, exciton C located at 450.82 nm is also observed in Fig. 2(c), which is due to the band-nesting effect and further results in a strong optical absorption even for excitation energy far beyond the bandgap value. Based on the Beer–Lambert law,  $I_t = I_0 e^{-\alpha t}$ , where  $I_t$  is the intensity of transmitted light,  $I_0$  is the intensity of original light,  $\alpha$  is the absorption coefficient, and  $t$  is the MoS<sub>2</sub> thickness. The “absorbance  $A$ ” is defined as  $A = \log_{10}(I_0/I_t)$ . For example, 90% of light is absorbed when the value of absorbance  $A$  is 1. As shown in Fig. 2(c), the values of absorbance  $A$  of the MoS<sub>2</sub> film are 1.19, 1.02, and 0.96, for wavelengths of 405, 532, and 638 nm, respectively, indicating 94%, 90%, and 89% of incident light intensity is absorbed at that specific wavelength. Lasers with these three different wavelengths (405, 532, and 638 nm) are chosen for phototransistor study later. By decreasing the wavelength from 638 to 405 nm, the absorption rate is increased for MoS<sub>2</sub> film grown on GaN. The absorption coefficient  $\alpha$  can be calculated using the equation:  $\alpha = \ln(10)A/t$ . Therefore, the calculated values of absorption coefficient  $\alpha$  are  $5.45 \times 10^6 \text{ cm}^{-1}$ ,  $4.70 \times 10^6 \text{ cm}^{-1}$ , and  $4.42 \times 10^6 \text{ cm}^{-1}$ , at wavelengths of 405, 532, and 638 nm, respectively [37]. The obtained value of absorption coefficient  $\alpha$  for MoS<sub>2</sub>-on-GaN film is about 1 order of magnitude higher than that reported for MoS<sub>2</sub>-on-SiO<sub>2</sub> film, which could lead to a highly responsive MoS<sub>2</sub> phototransistor. The high absorption coefficient  $\alpha$  for MoS<sub>2</sub>-on-GaN film could be due to the high-quality MoS<sub>2</sub> film grown on the nearly lattice-matched and smaller thermal expansion mismatch FS GaN substrate.

Figure 3(a) shows the fabricated MoS<sub>2</sub> phototransistors on a transparent FS GaN sample with a size of 1 cm by 1 cm, in which a device array has been fabricated. With the method proposed in this work, it can be used for fabricating MoS<sub>2</sub> phototransistors on a large scale. Figure 3(b) shows the 3D schematic view of the MoS<sub>2</sub>-on-GaN phototransistor on the transparent FS GaN wafer, and the device footprint size is  $\sim 0.01 \text{ cm}^2$ , with an active area of  $0.0008 \text{ cm}^2$ . As shown in Fig. 3(c), the current ratio of light/dark for the fabricated MoS<sub>2</sub>-on-GaN phototransistors is  $\sim 10^1$ – $10^2$  at applied voltage of 10 V and incident power of 10 mW, with a laser spot diameter of 2 mm. It is noted that the photocurrent under a 405 nm laser illumination is about  $\sim 3$ – $4$  times higher than that under a 638 nm laser illumination, which is due to both the high absorption ratio and photocurrent gain mechanism. Photocurrent  $I_{\text{ph}}$  under different incident powers of the MoS<sub>2</sub>-on-GaN phototransistor was measured under three laser wavelengths of 638, 532, and 405 nm, respectively. The photocurrent generated from the MoS<sub>2</sub>-on-GaN phototransistor is solely determined by the incident power at a constant voltage. The photogating



**Fig. 3.** (a) Photo image of the fabricated transparent ML MoS<sub>2</sub>-on-GaN phototransistors; (b) 3D schematic view of the MoS<sub>2</sub>-on-GaN phototransistor on a transparent FS GaN wafer; (c) the current ratio of light/dark for the fabricated MoS<sub>2</sub>-on-GaN phototransistors is  $\sim 10^1$ – $10^2$  at an applied voltage of 10 V and incident power of 10 mW with a laser spot diameter of 2 mm.

effect, due to the trapped electrons/holes underneath the channel, is not observed for MoS<sub>2</sub>-on-GaN phototransistors, which is due to the high quality and large bandgap of GaN, as compared with the case of MoS<sub>2</sub>-based photodetectors using a SiO<sub>2</sub>/Si wafer. To quantify the photosensitivity of the fabricated phototransistor, the photoresponsivity  $R$  is calculated by the expression:  $R = I_{\text{ph}}/(\text{power density} \times \text{active area})$ , where the photocurrent  $I_{\text{ph}}$  is defined as  $I_{\text{ph}} = I_{\text{light}} - I_{\text{dark}}$ . As shown in Figs. 4(a)–4(c), photoresponsivity  $R$  under three laser wavelengths of 638, 532, and 405 nm, respectively, is plotted as a function of incident laser power. It is observed that the photoresponsivity  $R$  is slightly increased as the incident laser power decreases, which is also reported in MoS<sub>2</sub> and other 2D material (black phosphorus, BP)-based phototransistors [1,15,38].



**Fig. 4.** Photoresponsivity  $R$  under three laser wavelengths of (a) 638, (b) 532, and (c) 405 nm plotted as a function of incident laser power. (d) Photoresponsivity  $R$  as a function of applied voltage for three laser wavelengths (638, 532, and 405 nm) at a laser power of 2 mW; (e) photoconductive gain  $G$  and EQE as a function of the incident wavelength with an applied voltage of 9 V and power of 2 mW; (f) specific detectivity  $D$  and NEP as a function of the incident wavelength with an applied voltage of 9 V and power of 2 mW.

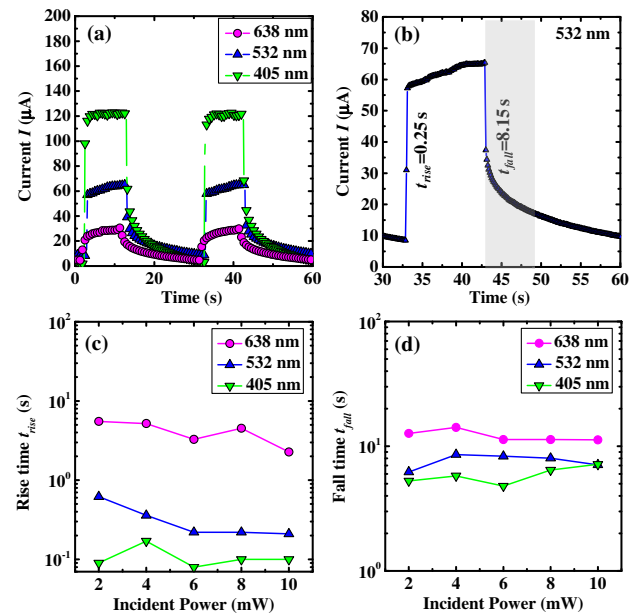
This could be due to less frequent carrier recombination and longer carrier lifetime under a weaker illumination. Figure 4(d) shows photoresponsivity  $R$  as a function of applied voltage for three laser wavelengths at a laser power of 2 mW. At 2 mW laser illumination power, a peak photoresponsivity  $R$  of 0.59, 2.78, and 17.2 A/W is obtained for a laser wavelength of 638, 532, and 405 nm, respectively. By increasing the voltage, the photoresponsivity  $R$  is linearly increased in Fig. 4(d). Under a higher applied voltage, the electrical field across the active region is increased, which increases the drift velocity of photo-generated electron-hole carriers or increases the photogenerated current, leading to a larger photoresponsivity  $R$ . Also, it is noted that a larger photoresponsivity  $R$  is obtained at a shorter wavelength (405 nm), as compared with the other two wavelengths (638 and 532 nm); this is due to the higher light absorption at 405 nm, as shown in Fig. 2(c). This wavelength-dependent photoresponsivity corresponds well with the fact that higher excitation energy enhances the conversion of photoelectronics.

To further evaluate the performance of the MoS<sub>2</sub>-on-GaN phototransistor, photoconductive gain  $G$  and external quantum efficiency (EQE) are also calculated and shown in Fig. 4(e). Photoconductive gain  $G$ , indicating how many carriers of the photocurrent can be generated by one absorbed photon, can be estimated by the equation  $G = (I_{ph}/P_{abs})(h\nu/q)$ , where  $P_{abs}$  is the power absorbed,  $h$  is Planck's constant,  $\nu$  is the frequency of the incident laser, and  $q$  is the elementary charge. The value of  $P_{abs}$  equals  $\mu P_{in}$ , where  $\mu$  is the absorption percentage and  $P_{in}$  is the incident power. The absorption percentage at a specific wavelength has been discussed in Fig. 2(c). As the laser wavelength decreases from 638 to 405 nm, the photoconductive gain  $G$  is increased from 1.3 to 56.3, indicating that a larger number of photogenerated electron-hole carriers are populated. EQE, defined as the number of photogenerated carriers collected per incident photon, can be calculated by the equation  $EQE = R \times (h\nu/q)$ . As shown in Fig. 4(e), EQE increased from 115% to 5289%, as the laser wavelength decreased from 638 to 405 nm. The maximum photoresponsivity  $R$  of 17.2 A/W, the maximum photoconductive gain  $G$  of 56.3, and the maximum EQE of 5289% are obtained under a 405 nm laser illumination at an applied voltage of 9 V and power of 2 mW, which is better than the reported values for MoS<sub>2</sub> and other 2D material (BP)-based phototransistors [38].

To evaluate the detection limit of our device and assume the short noise from the dark current is the major contributor to the total noise, the specific detectivity  $D$  is calculated by the equation  $D = A^{1/2}/NEP$ , where  $A$  is the device active area, and NEP is the noise equivalent power and defined as the excitation power needed to generate a signal equal to the noise level in the 1 Hz bandwidth. NEP can be estimated by the equation  $NEP = (2qI_{dark}\Delta f)^{1/2}/R$ , where  $I_{dark}$  is the dark current,  $\Delta f$  is the bandwidth, and  $R$  is the photoresponsivity. With the measured wavelength range of 405–638 nm, the specific detectivity  $D$  is  $\sim 6.3 \times 10^{10}$ – $1.8 \times 10^{12}$  Jones, and the NEP is  $\sim 2.8 \times 10^{-12}$ – $9.6 \times 10^{-14}$  W/Hz<sup>1/2</sup>, as shown in Fig. 4(f). The low NEP of the MoS<sub>2</sub>-on-GaN phototransistor has the potential to detect subpicowatt illumination power with half-a-second integration time. Although the performance of the MoS<sub>2</sub>-on-GaN phototransistor in this work shows much

inferior performance to a silicon photodiode ( $R$  of  $\sim 300$  A/W and  $D$  of  $\sim 10^{13}$  Jones) [37], their performance is better than phototransistors based on graphene ( $R$  of  $\sim 1$ – $6.1$  mA/W) or single layer MoS<sub>2</sub> ( $R$  of 7.5 mA/W). In addition, the MoS<sub>2</sub>-on-GaN phototransistor in this work consists of a simple n-type channel, which is easier to fabricate than a Si p-n photodiode. Future work involving optimization of the device architecture and processing will greatly enhance the performance of MoS<sub>2</sub>-on-GaN phototransistors.

Photoswitching characteristics have also been investigated under the three different laser illuminations (638, 532, and 405 nm) for various incident powers at a fixed voltage of 3 V. The stability of the switching behavior is demonstrated by applying multiple illuminations on the device for 10 s. Figure 5(a) shows the photocurrent as a function of time under the alternative dark and illumination conditions at different laser wavelengths with a fixed incident power of 6 mW and a fixed voltage of 3 V. Under illumination, the current rises to a high value (on-state) and then returns to a low value (off-state) when the light is off. The rise and fall times are taken from 10% to 90% of the maximum photocurrent and from 90% to 10% of the maximum photocurrent, respectively, as shown in Fig. 5(b). Figures 5(c) and 5(d) show the rise time  $t_{rise}$  and fall time  $t_{fall}$  as functions of the incident power for three different laser illuminations (638, 532, and 405 nm) with a fixed voltage of 3 V. The rise time  $t_{rise}$  shows wavelength-dependent behavior, but is less sensitive to the incident power. As the illumination laser wavelength decreases from 638 to 405 nm, the average rise time  $t_{rise}$  decreases from 4.2 s to



**Fig. 5.** (a) Photocurrent as a function of time under the alternative dark and illumination conditions at different laser wavelengths (638, 532, and 405 nm) with a fixed incident power of 6 mW and a fixed voltage of 3 V; (b) the rise and fall times are taken from 10% to 90% of the maximum photocurrent and from 90% to 10% of the maximum photocurrent, respectively. (c) Rise time  $t_{rise}$  and (d) fall time  $t_{fall}$  as a function of incident power for three different laser illuminations (638, 532, and 405 nm) with a fixed voltage of 3 V.

0.1 s. The value of rise time  $t_{\text{rise}}$  depends on a charging or trapping process under the laser illumination. The rise time  $t_{\text{rise}}$  obtained here is still lower as compared with that of graphene (tens of picoseconds), as the carrier transport in graphene is ballistic and very fast [39–41], but is comparable to the reported monolayer MoS<sub>2</sub>-based phototransistors [1]. The field effective mobility is extracted from the fabricated MoS<sub>2</sub> field effect transistor, and the average value of the field effective mobility is about  $3.5 \text{ cm}^2 \cdot \text{V}^{-1} \cdot \text{s}^{-1}$ . By further enhancing the carrier mobility of MoS<sub>2</sub>, such as oxide passivation, the rise time  $t_{\text{rise}}$  here can be further reduced. As discussed in Fig. 2(c), it is noted that the absorption rate is higher under a 405 nm laser illumination, leading to generating more electron-hole carriers at a given time and filling up traps within the channel in a shorter duration. This explains that the MoS<sub>2</sub>-on-GaN phototransistor shows a shorter rise time for shorter laser wavelengths. When the laser is switched off, the photocurrent does not decrease to the dark level immediately, but exponentially decreases. The observation of a persistent photocurrent is due to the trapped long-range Coulomb potentials, which could be from the charged impurities at the MoS<sub>2</sub>/GaN interface or within MoS<sub>2</sub>, thus drastically affecting the recombination of electron-hole pairs. The photocurrent during the fall time can be fitted using the equation  $I_{\text{ph}} = I_{\text{dark}} + B \exp(t/\tau)$ , where  $B$  is a scaling constant,  $t$  is the time, and  $\tau$  is the time constant of the traps or relaxation time constant. The fitted relaxation time constant of the three laser wavelength cases is almost identical ( $\sim 9.13$  s), which explains that the fall time  $t_{\text{fall}}$  is less sensitive to the laser wavelength, since the fall time is dominated by the discharging or detrapping process, which is only related to the traps within the MoS<sub>2</sub>-on-GaN sample. The MoS<sub>2</sub>-on-GaN phototransistor in this work shows a typical rise time  $t_{\text{rise}}$  of 0.1–4 s and fall time  $t_{\text{fall}}$  of 9 s, which is similar to the corresponding value observed in the mechanical exfoliated monolayer MoS<sub>2</sub> phototransistor and graphene-quantum dot values [41]. It is believed that the surrounding of the MoS<sub>2</sub> plays an important role in photocurrent switching behavior, with different surface treatment able to reduce the fall time in the 0.3–4000 s range, due to the differences in surface hydrophobicity [42,43]. The photocurrent switching performance of the MoS<sub>2</sub>-on-GaN phototransistor can be further improved by proper device passivation or an encapsulating technique.

#### 4. CONCLUSION

Using the one-step CVD growth method, high-quality and large-scale ML MoS<sub>2</sub> film has been grown on a transparent nearly lattice-matched FS GaN wafer, which can be called transparent “MoS<sub>2</sub>-on-GaN” technology. The fabricated MoS<sub>2</sub>-on-GaN phototransistor shows high responsivity of 17.2 A/W at a laser wavelength of 405 nm, due to the high absorption coefficient of MoS<sub>2</sub>-on-GaN film. In addition, high photocurrent gain, high EQE, high specific detectivity, and low NEP have been achieved for a transparent ML MoS<sub>2</sub>-on-GaN phototransistor in the visible range (405, 532, and 638 nm), and it shows robust on/off photocurrent switching with a typical response time of 0.1–4 s. Transparent “MoS<sub>2</sub>-on-GaN” technology developed in this work can be attractive for a variety

of industry transparent applications, including touch-sensor panels, image sensors, and communication devices.

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